

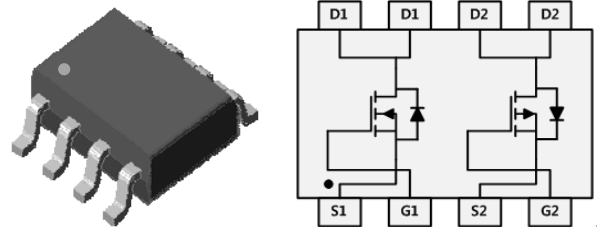
## 30V Dual N- and P-channel Trench MOSFET

### Features

- Low  $V_{GS(th)}$ :  $V_{GS(th)}=1.0\sim 3.0V$
- Small footprint due to small package
- Low  $R_{GDS(on)}$ : N-ch,  $R_{DS(on)}=24m\Omega$  (@  $V_{GS}=10V, I_D=2.9A$ )  
P-ch,  $R_{DS(on)}=66m\Omega$  (@  $V_{GS}=-10V, I_D=-2.7A$ )

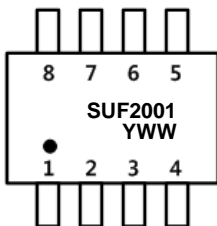
### Ordering Information

Part Number	Marking Code	Package
SUF2001	SUF2001	SOP-8



SOP-8

### Marking Information



Column 1: Device Code  
 Column 2: Production Information  
 -. Y: Year Code  
 -. WW: Week Code

### Absolute maximum ratings ( $T_A=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Rating		Unit
		N-Ch	P-Ch	
Drain-source voltage	$V_{DSS}$	30	-30	V
Gate-source voltage	$V_{GSS}$	$\pm 20$		V
Drain current (DC)	$I_D$	5.8	-5.3	A
Drain current (Pulsed) *	$I_{DP}$	23.2	-21.2	A
Total power dissipation **	$P_D$	2		W
Avalanche current (Single)	$I_{AS}$	5.8 <sup>②</sup>	-5.3 <sup>⑥</sup>	A
Single pulsed avalanche energy	$E_{AS}$	72 <sup>②</sup>	33 <sup>⑥</sup>	mJ
Avalanche current (Repetitive) <sup>①</sup>	$I_{AR}$	5.8	-5.3	A
Repetitive avalanche energy <sup>①</sup>	$E_{AR}$	3.4	1.6	mJ
Junction temperature	$T_J$	150		°C
Storage temperature range	$T_{stg}$	-55~150		
Thermal resistance junction to ambient	$R_{th(J-A)}$	62.5		°C/W

\* Limited by maximum junction temperature

\*\* Device mounted on a glass-epoxy board

## N-channel MOSFET Electrical Characteristics

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0$	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu A, V_{DS}=V_{GS}$	1.0	-	3.0	V
Drain-source cut-off current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate leakage current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=2.9A$	-	24	30	$m\Omega$
		$V_{GS}=5.0V, I_D=2.9A$	-	28	34	$m\Omega$
Forward transfer conductance <sup>④</sup>	$g_{fs}$	$V_{DS}=5V, I_D=5.8A$	-	12	-	S
Input capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=10V, f=1MHz$	-	370	560	pF
Output capacitance	$C_{oss}$		-	60	90	
Reverse transfer capacitance	$C_{rss}$		-	36	54	
Turn-on delay time <sup>③④</sup>	$t_{d(on)}$	$V_{DS}=15V, I_D=5.8A, R_G=10\Omega$	-	1.2	-	ns
Rise time <sup>③④</sup>	$t_r$		-	1.1	-	
Turn-off delay time <sup>③④</sup>	$t_{d(off)}$		-	2.5	-	
Fall time <sup>③④</sup>	$t_f$		-	1.1	-	
Total gate charge <sup>③④</sup>	$Q_g$	$V_{DS}=15V, V_{GS}=5V, I_D=5.8A$	-	4.2	6.3	nC
Gate-source charge <sup>③④</sup>	$Q_{gs}$		-	0.9	1.4	
Gate-drain charge <sup>③④</sup>	$Q_{gd}$		-	1.4	2.1	

## Source-Drain Diode Ratings and Characteristics

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current	$I_S$	Integral reverse diode in the MOSFET	-	-	1.5	A
Source current(Pulsed) <sup>①</sup>	$I_{SM}$		-	-	6.0	
Forward voltage <sup>④</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1.5A$	-	-	1.2	V
Reverse recovery time	$t_{rr}$	$I_S=1.5A, di_S/dt=100A/us$	-	90	-	ns
Reverse recovery charge	$Q_{rr}$		-	0.5	-	$\mu C$

Note ;

- ① Repetitive Rating : Pulse width limited by maximum junction temperature
- ②  $L=3.4mH, I_{AS}=5.8A, V_{DD}=15V, R_G=25\Omega$
- ③ Pulse Test : Pulse Width < 300us, Duty cycle $\leq$ 2%
- ④ Essentially independent of operating temperature

## P-channel MOSFET Electrical Characteristics

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0$	-30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu A, V_{DS}=V_{GS}$	-1.0	-	-3.0	V
Drain-source cut-off current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate leakage current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-2.7A$	-	66	72	m $\Omega$
		$V_{GS}=-5.0V, I_D=-2.7A$	-	77	83	m $\Omega$
Forward transfer conductance <sup>⑧</sup>	$g_{fs}$	$V_{DS}=-5V, I_D=-5.3A$	-	11	-	S
Input capacitance	$C_{iss}$	$V_{GS}=0V, V_{DD}=-10V, f=1MHz$	-	390	590	pF
Output capacitance	$C_{oss}$		-	97	150	
Reverse transfer capacitance	$C_{rss}$		-	37	60	
Turn-on delay time <sup>⑦⑧</sup>	$t_{d(on)}$	$V_{DS}=-15V, I_D=-5.3A, R_G=10\Omega$	-	1.2	-	ns
Rise time <sup>⑦⑧</sup>	$t_r$		-	1.1	-	
Turn-off delay time <sup>⑦⑧</sup>	$t_{d(off)}$		-	2.5	-	
Fall time <sup>⑦⑧</sup>	$t_f$		-	1.1	-	
Total gate charge <sup>⑦⑧</sup>	$Q_g$	$V_{DS}=-15V, V_{GS}=-5V, I_D=-5.3A$	-	4.7	7.0	nC
Gate-source charge <sup>⑦⑧</sup>	$Q_{gs}$		-	1.4	2.1	
Gate-drain charge <sup>⑦⑧</sup>	$Q_{gd}$		-	1.7	2.5	

## Source-Drain Diode Ratings and Characteristics

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current	$I_S$	Integral reverse diode in the MOSFET	-	-	-1.5	A
Source current (Pulsed) <sup>⑤</sup>	$I_{SM}$		-	-	-6.0	
Forward voltage <sup>⑥</sup>	$V_{SD}$	$V_{GS}=0V, I_S=-1.5A$	-	-	-1.2	V
Reverse recovery time	$t_{rr}$	$I_S=-1.5A, di_s/dt=100A/\mu s$	-	90	-	ns
Reverse recovery charge	$Q_{rr}$		-	0.5	-	$\mu C$

Note ;

- ⑤ Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ⑥  $L=2.0mH, I_{AS}=-5.0A, V_{DD}=-15V, R_G=25\Omega$
- ⑦ Pulse Test : Pulse Width < 300 $\mu s$ , Duty cycle $\leq 2\%$
- ⑧ Essentially independent of operating temperature

N-CH Electrical Characteristic Curves

Fig. 1  $I_D - V_{DS}$

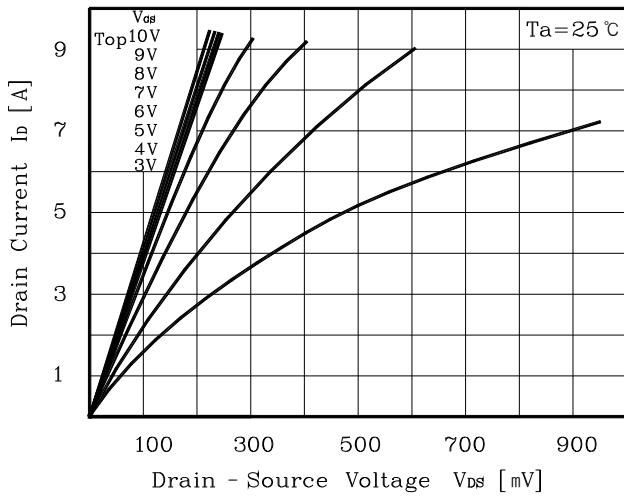


Fig. 2  $I_D - V_{GS}$

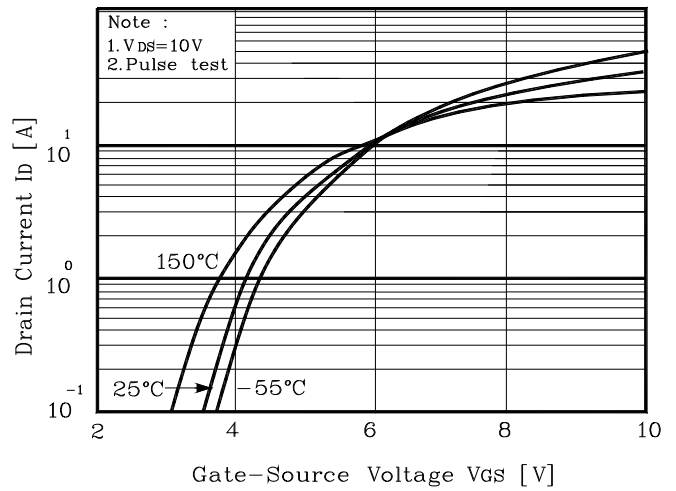


Fig. 3  $R_{DS(on)} - I_D$

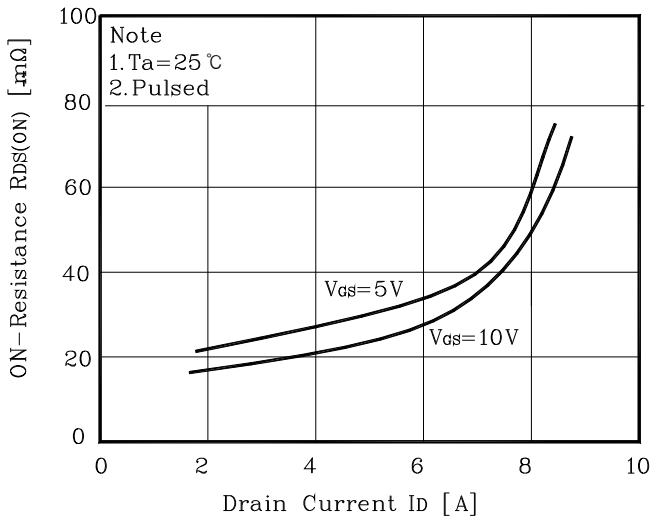


Fig. 4  $I_S - V_{SD}$

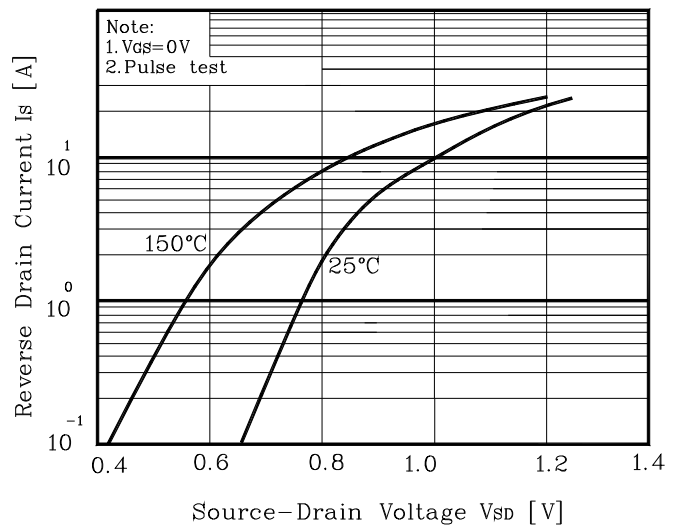


Fig. 5 Capacitance -  $V_{DS}$

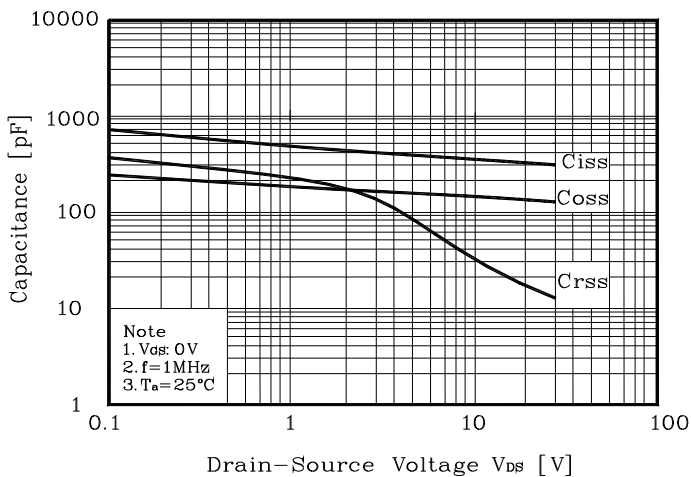
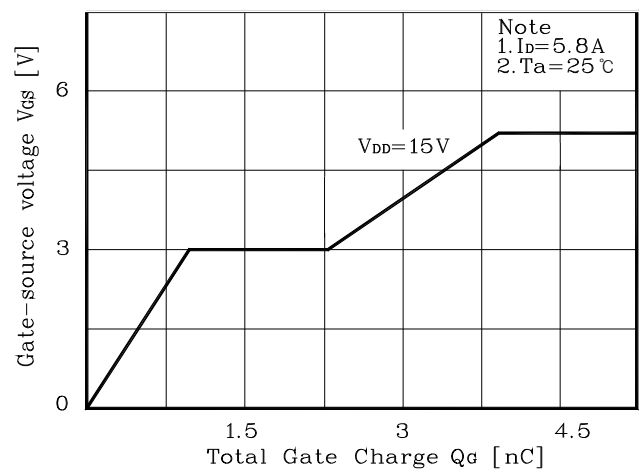
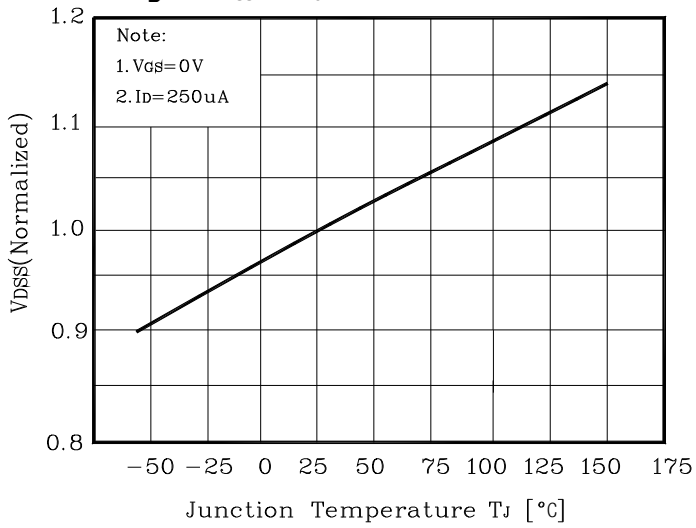


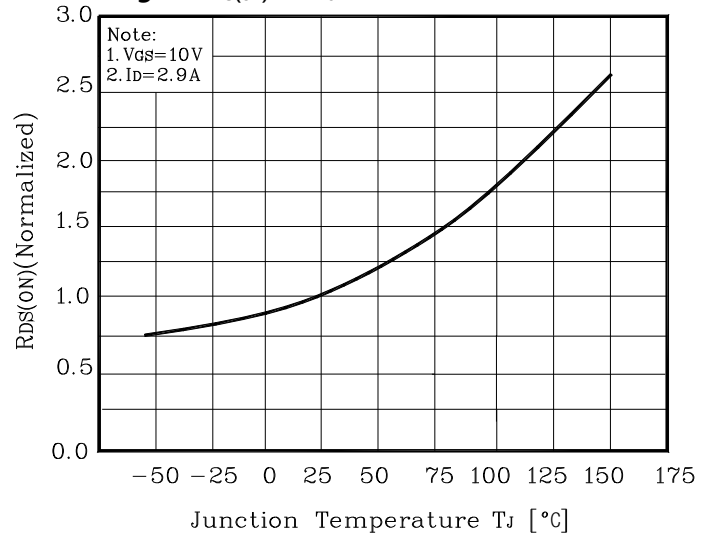
Fig. 6  $V_{GS} - Q_G$



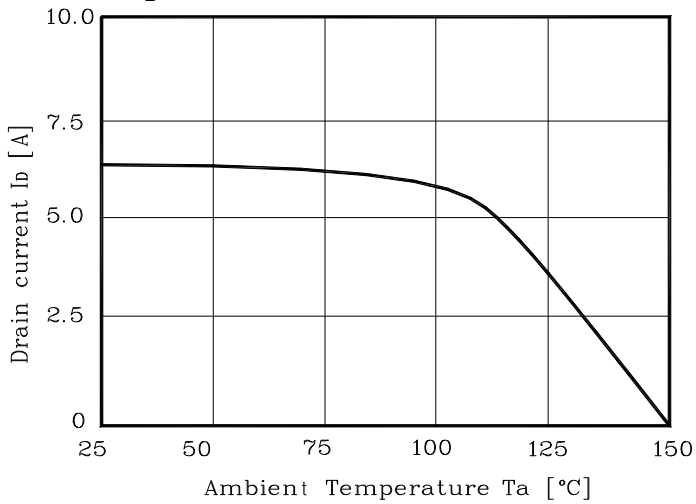
**Fig. 7  $V_{DSS} - T_J$**



**Fig. 8  $R_{DS(on)} - T_J$**



**Fig. 9  $I_D - T_a$**



**Fig. 10 Safe Operating Area**

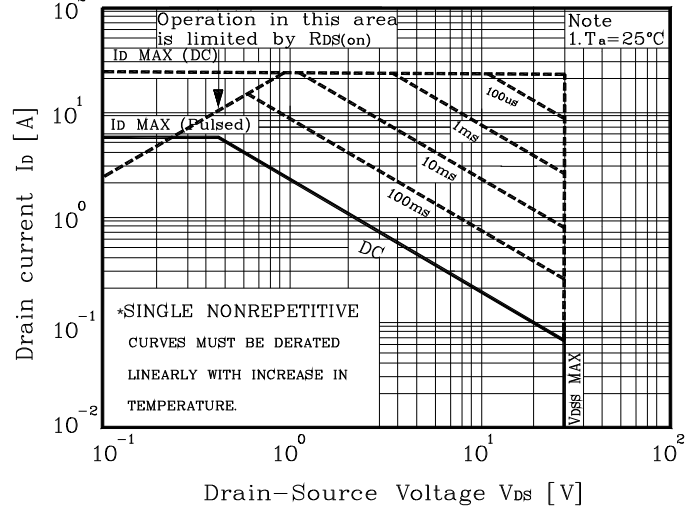


Fig. 11 Gate Charge Test Circuit & Waveform

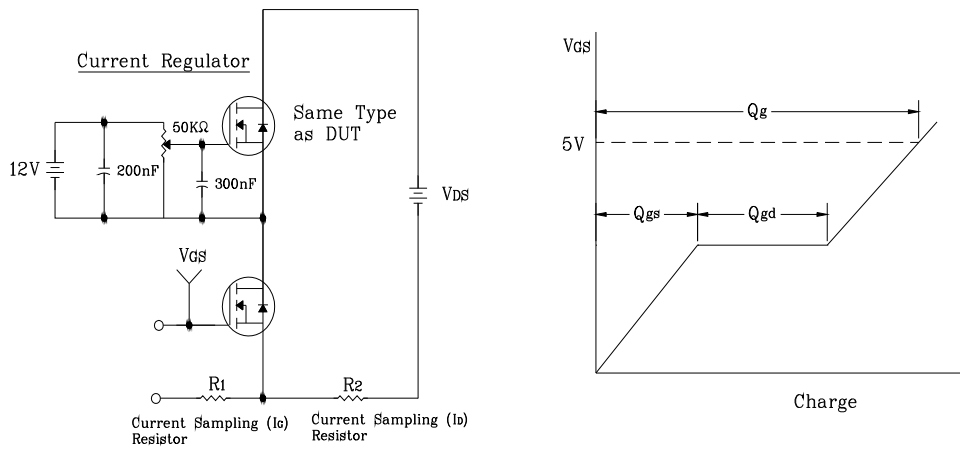


Fig. 12 Resistive Switching Test Circuit & Waveform

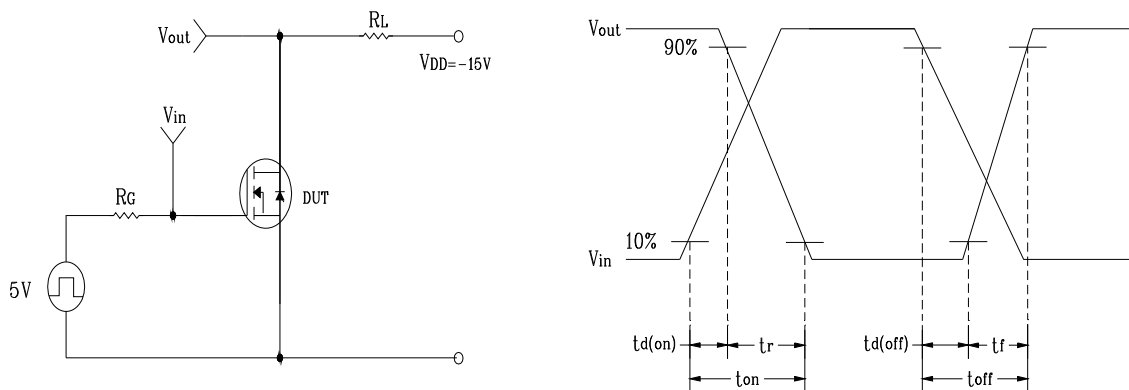


Fig. 13 EAS Test Circuit & Waveform

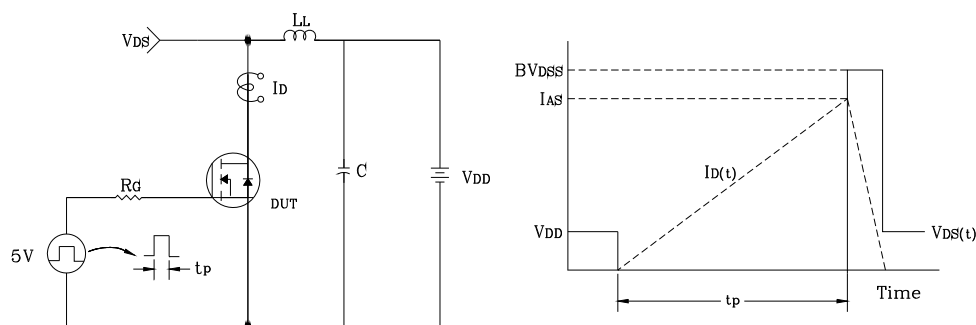
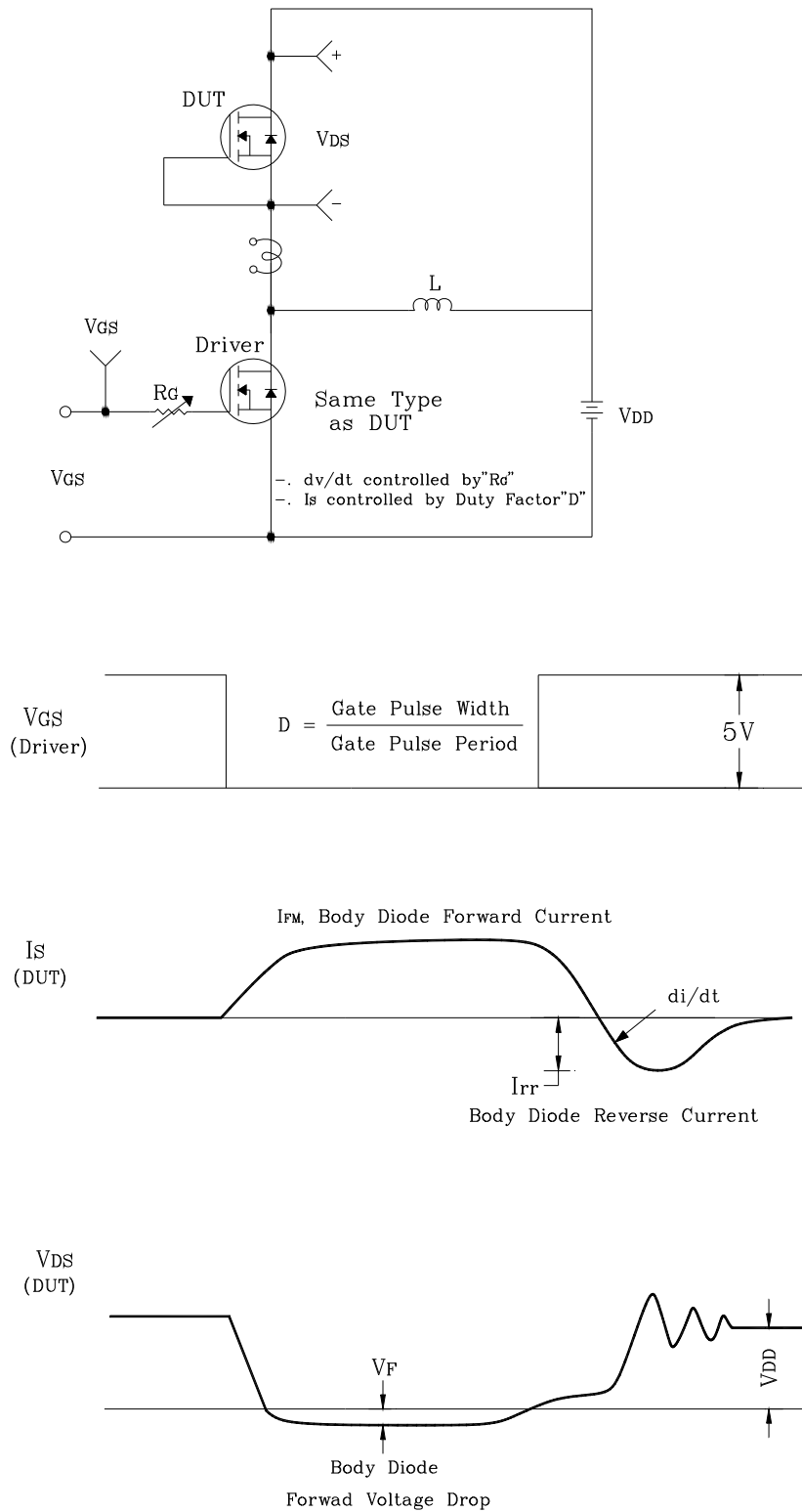


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform



P-CH Electrical Characteristic Curves

Fig. 1  $I_D - V_{DS}$

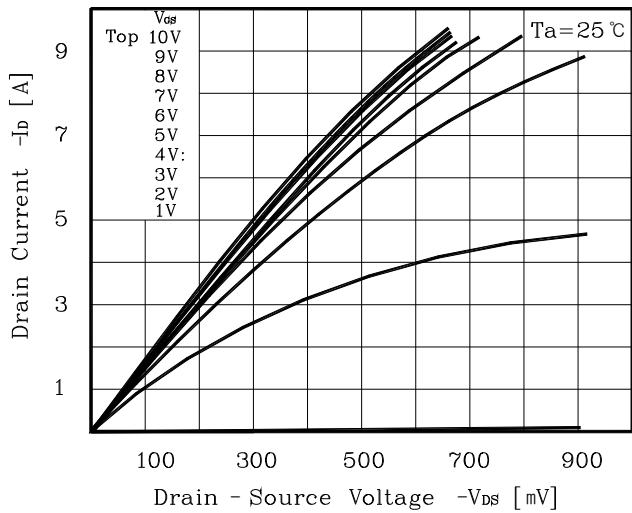


Fig. 2  $I_D - V_{GS}$

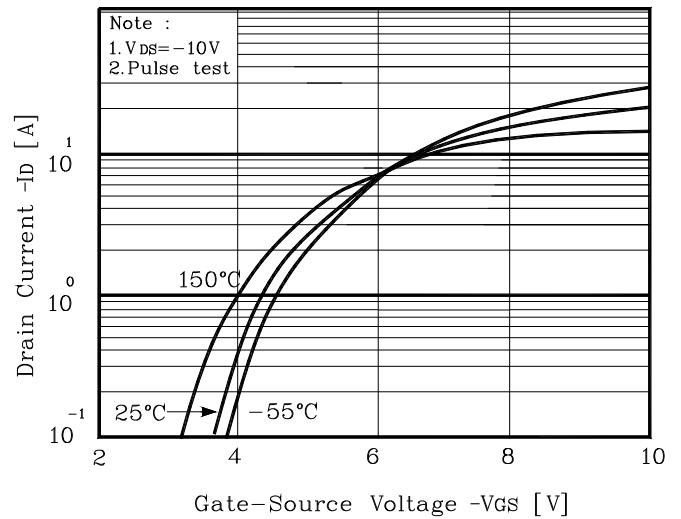


Fig. 3  $R_{DS(on)} - I_D$

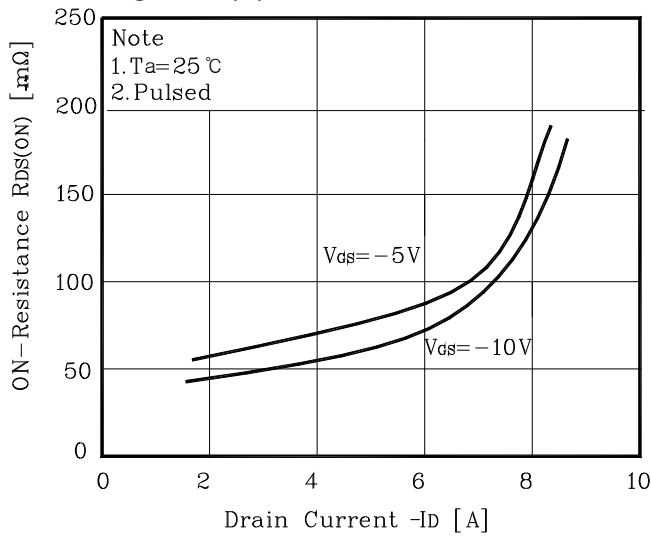


Fig. 4  $I_S - V_{SD}$

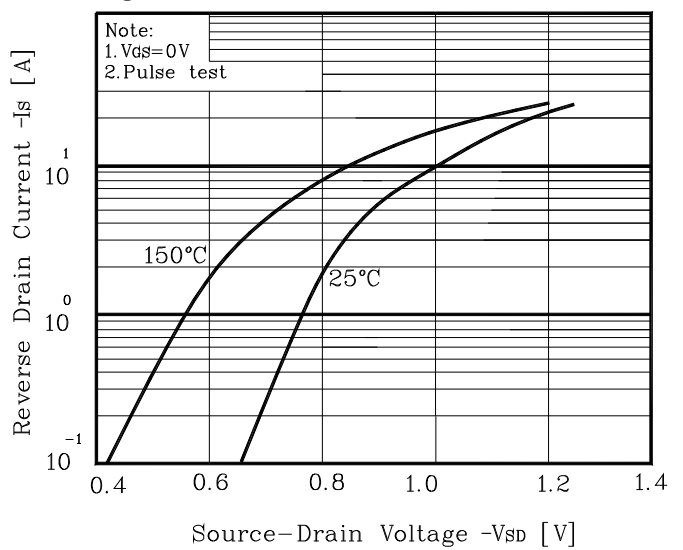


Fig. 5 Capacitance -  $V_{DS}$

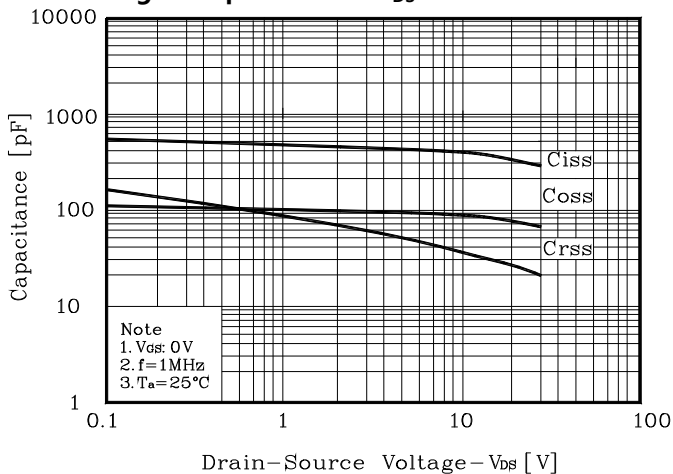
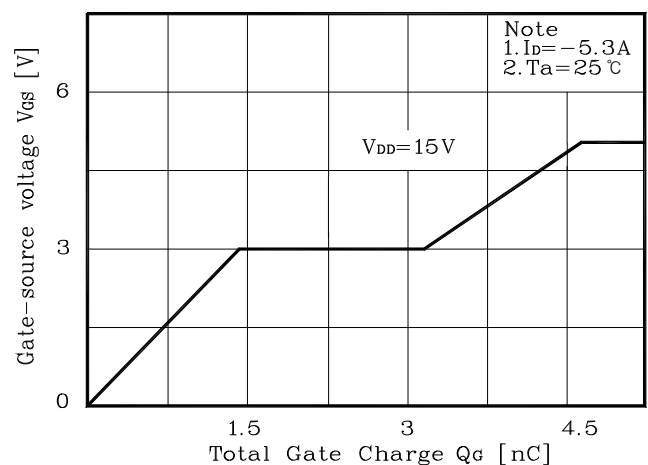
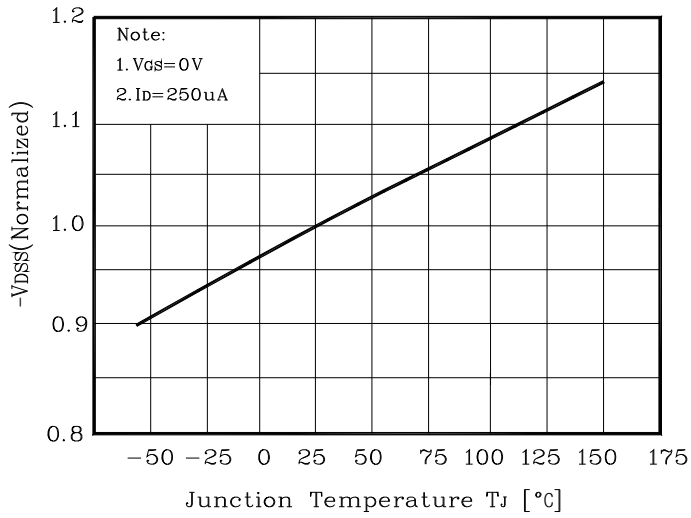


Fig. 6  $V_{GS} - Q_G$

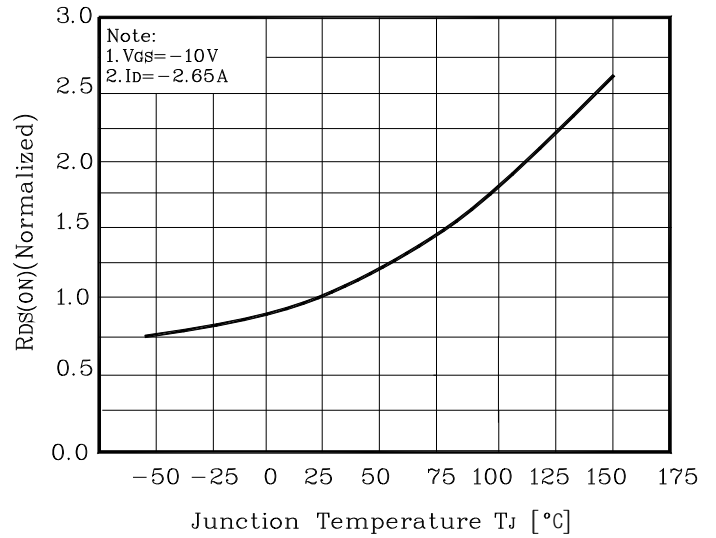




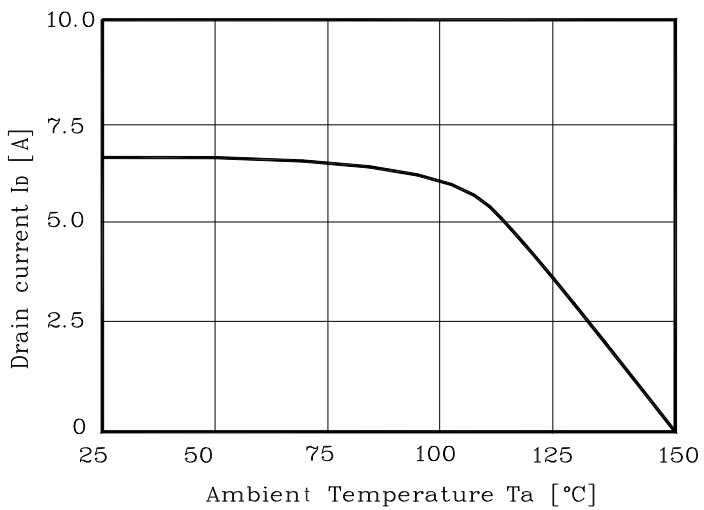
**Fig. 7  $V_{DSS} - T_J$**



**Fig. 8  $R_{DS(on)} - T_J$**



**Fig. 9  $I_D - T_a$**



**Fig. 10 Safe Operating Area**

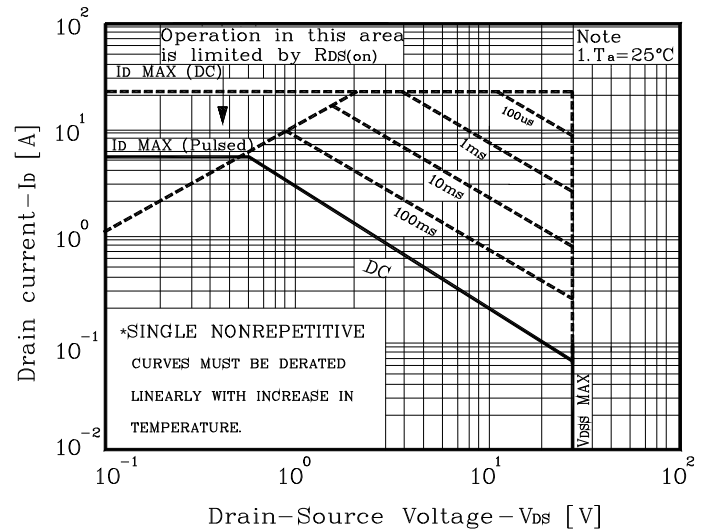


Fig. 11 Gate Charge Test Circuit & Waveform

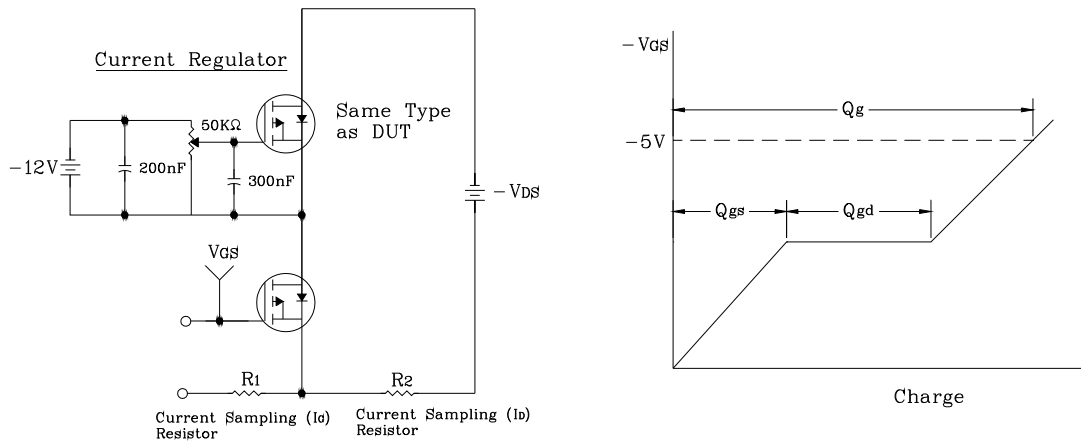


Fig. 12 Resistive Switching Test Circuit & Waveform

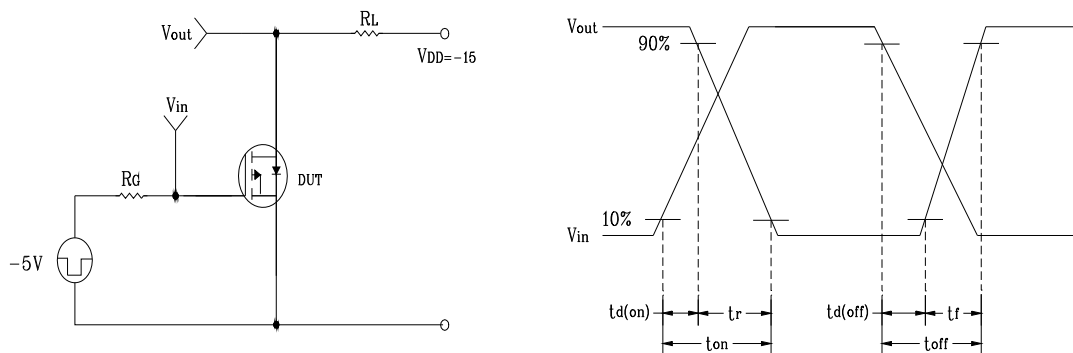


Fig. 13 E<sub>AS</sub> Test Circuit & Waveform

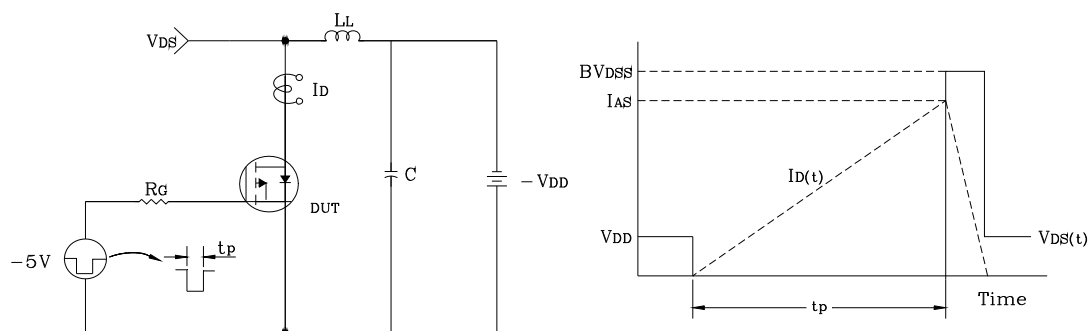
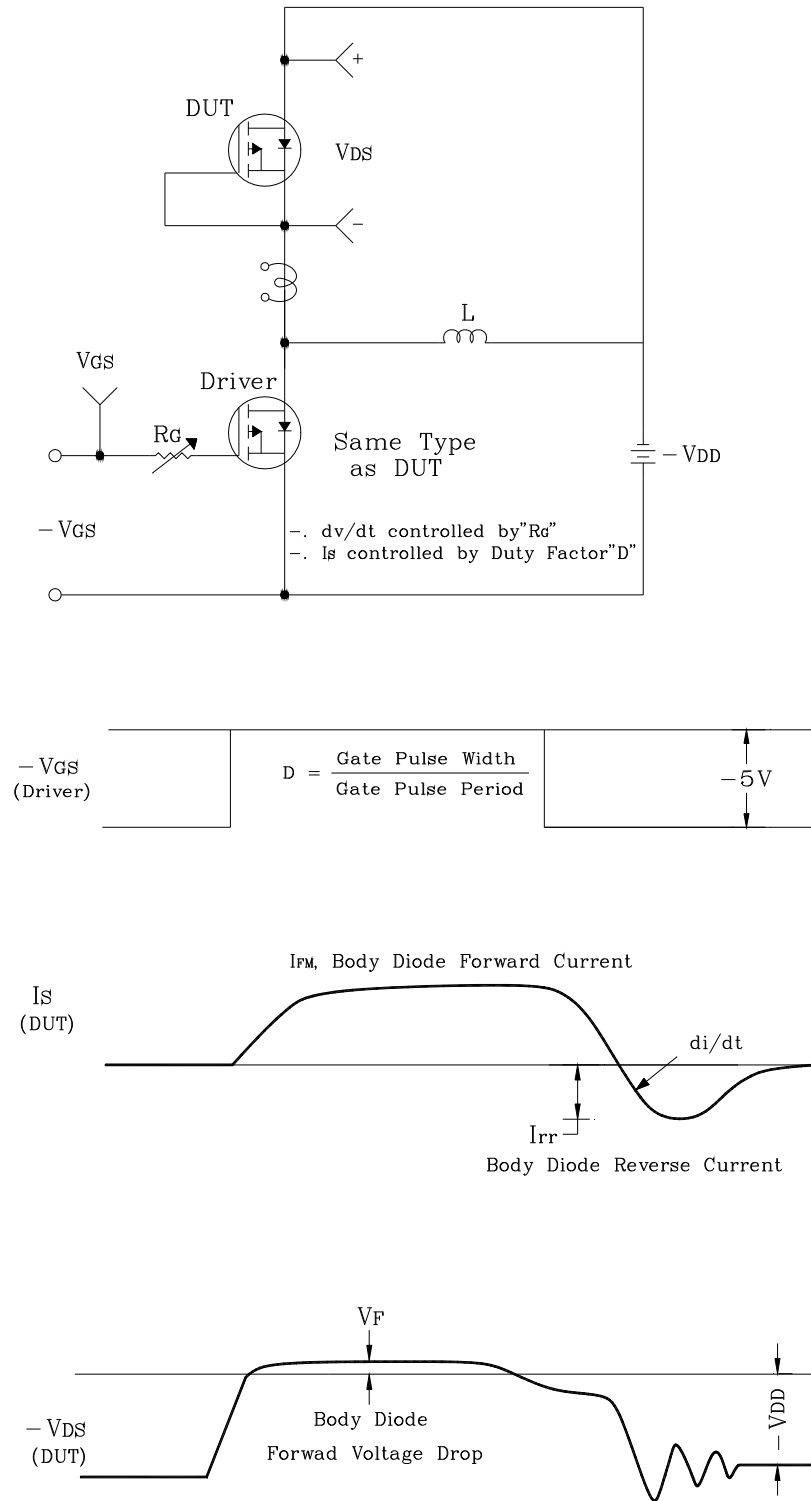
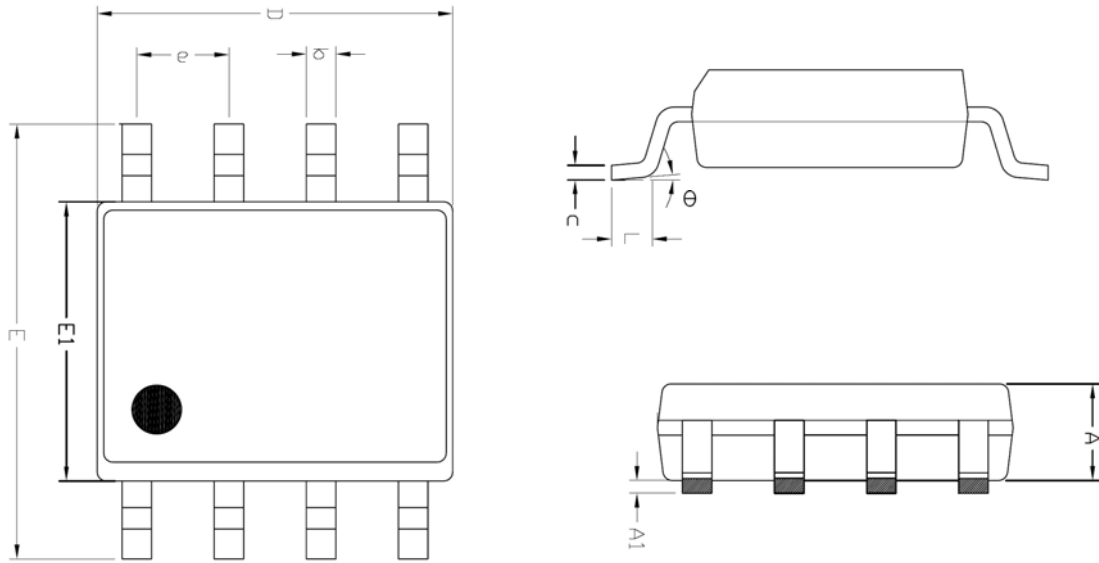


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform

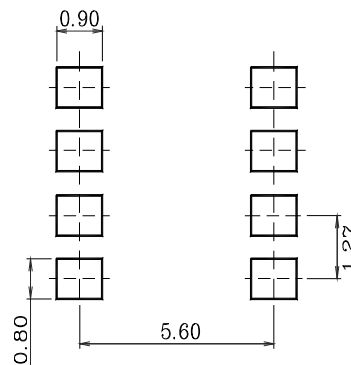


Package Outline Dimensions



SYMBOL	MILLIMETER(mm)			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	1.245	-	1.445	
A1	0.125	0.175	0.275	
b	0.320	0.420	0.520	
c	0.170	0.220	0.270	
D	4.802	4.902	5.002	
E	5.870	6.020	6.170	
E1	3.761	3.861	3.961	
e	1.270 BSC			
L	0.462	0.562	0.662	
theta	0 °	-	8 °	

※ Recommended Land Pattern [unit: mm]



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